Two-Piece Vapor Chambers

Limitless Design Options

Thicknesses from 2.5mm to 25mm that can be stamped or machined into virtually any shape and can include variable porosity wick structures.

Powerful Heat Spreading Capability

From cooling power densities up to 500 W/cm^2 to effectively working against gravity, Celsia vapor chambers consistently test at the top of the performance spectrum.

4-Factor Optimization

We strive to develop thermal solutions that balance performance, weight, cost and manufacturability.

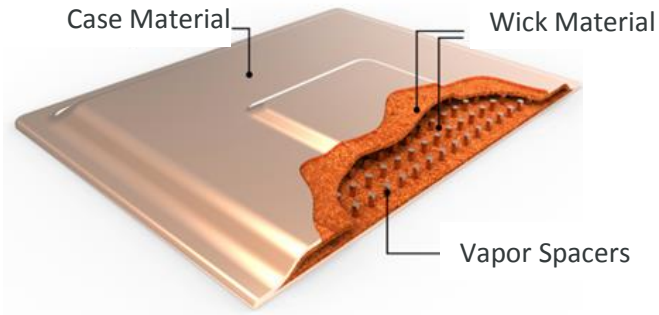
Ideal for Difficult Thermal Applications

We specialize in complete thermal solutions using liquid two-phase devices. If the physics permit, we know how to design and manufacture it.

Revision 1.1

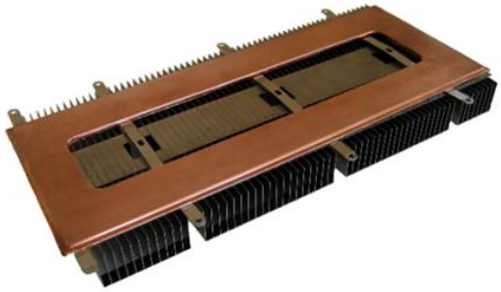
Heat Spreading & Transport in any Shape

Whether the problem is high power density, recessed heat sources or harsh environments, **Celsia designs meet tough mechanical and performance goals**.

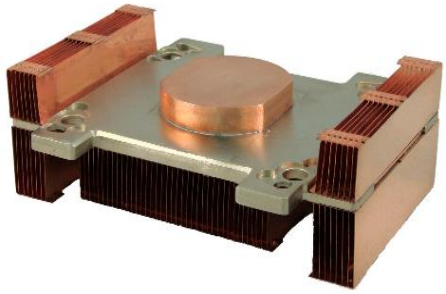


Constant Innovation – Our thermal design teams work daily with manufacturing engineers to develop and refine unique approaches to liquid two-phase cooling solutions.

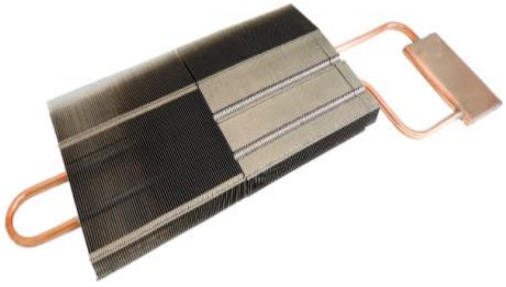
Project Examples



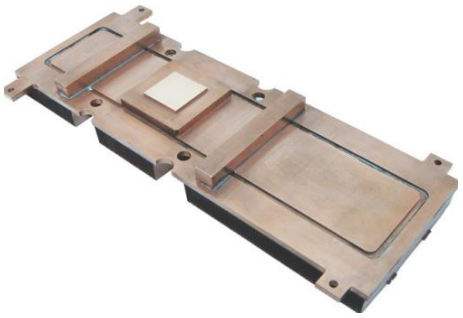
Multiple Heat Sources – Weight optimized telecom application requiring six heat sources maintain a Delta T of within 2° Celsius.



Recessed Heat Sources – Pedestal vapor chamber designed to cool high power CPU in a space constrained environment.



Looped Vapor Chamber – Simplified designs where high heat needs to be moved significant distances.



High Power – Single 300W CPU for high performance server application required all copper components and fin stack.

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celsia™
Making Hot Technology Cooler